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WHAT IS CLAIMED IS:

1. A wiring substrate, in which a wiring stacked portion including a conductor layer and a resin layer is stacked on a principal face of a core substrate including a substantially cylindrical through hole conductor in a through hole extending therethrough and a filling material filling the hollow portion of said through hole, comprising:
 - 10 a cover-shaped conductor portion covering an end face of said through hole just over a principal face of said core substrate and connected to said through hole conductor; and
 - 15 an internal conductor layer provided in said wiring stacked portion and across at least one of said resin layer from said cover-shaped conductor layer,
 - 20 wherein a connection portion composed of via conductors buried in said resin layer brings said cover-shaped conductor portion and said internal conductor layer into conduction, and said via conductors composing said connection portion are provided not above said through hole.
- 20 2. The wiring substrate according to claim 1,
 - 25 wherein at least two of said resin layer are sandwiched between said cover-shaped conductor layer and said internal conductor layer, and said via conductor composed of filled vias is buried in each of said resin layer and is stacked substantially

concentrically in plurality to construct said connection portion.

3. The wiring substrate according to claim 1, wherein
5 a distance from a center axis of said via conductor constructing
said connection portion to an outer edge of said through hole
is from 125 μm to 500 μm .

4. The wiring substrate according to claim 2, wherein
10 a distance from a center axis of said via conductor constructing
said connection portion to an outer edge of said through hole
is from 125 μm to 500 μm .

5. A wiring substrate comprising:
15 a core substrate including a through hole provided through
an insulating substrate, a substantially cylindrical through
hole conductors provided on an inner circumference of said
through hole, and a filling material filling a hollow portion
of said through hole conductors;
20 a first earthing conductor layer provided on at least one
principal face of said core substrate and in a shape containing
an end face of said through hole and having conduction to said
through hole conductor;
25 a plurality of resin layers provided over said first
earthing conductor layer;

a transmission line provided between any ones of said resin layers and positioned above said first earthing conductor layer;

5 a second earthing conductor layer provided over said resin layers and in a shape containing said transmission line; and

10 a connection portion including either: via conductors buried individually in said resin layers; or said via conductors and a third earthing conductor layer provided between the same resin layers as said transmission line and having no conduction to said transmission line, said via conductors being provided to bring said first earthing conductor layer and said second earthing conductor layer into conduction,

15 wherein said via conductors to be connected to said first earthing conductor layer are positioned in said connection portion so as not to be above said through hole.

6. The wiring substrate according to claim 5, wherein either a stacked via structure, in which a plurality of 20 filled vias are concentrically contiguous to each other at a position avoiding that above said through hole; or a structure, in which said third earthing conductor layer is connected between any contiguous ones of said filled vias in said stacked via structure

25 is provided.